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Title of Invention:

CHAMBER FOR A

SEMICONDUCTOR WAFER

HIGH-PRESSURE PROCESSING

First Named Inventor:

William Jones

Domestic/Foreign Application:

Domestic Application

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Attorney Docket Number:

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RADE Electronic Version v1.1

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Title of Invention

HIGH-PRESSURE PROCESSING CHAMBER FOR A SEMICONDUCTOR WAFER

Application Number:

10/680783

Date:

2003-10-06

First Named Applicant:

William Dale Jones

Confirmation Number:

5859

Attorney Docket Number:

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Thomas B. Haverstock Registered Number: 32571	/tbh/	Attorney	

Documents being submitted

Files

us-ids

SSI04001C-usidst.xml

us-ids.dtd us-ids.xsl

Comments



ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18
Stylesheet Version v18.0

Title of Invention

HIGH-PRESSURE PROCESSING CHAMBER FOR A SEMICONDUCTOR WAFER

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First Named Applicant:

William Jones

Attorney Docket Number:

Search string:

(5882165 or 5888050 or 5898727 or 5900107 or 5904737 or 5928389 or 5932100 or 5934856 or 5934991 or 5979306 or 5980648 or 5981399 or 5989342 or 6005226 or 6017820 or 6029371 or 6035871 or 6037277 or 6053348 or 6056008 or 6067728 or 6077053 or 6077321 or 6082150 or 6085935 or 6097015 or 6128830 or 6145519 or 6159295 or 6164297 or 6186722 or 6203582 or 6216364 or 6228563 or 6235634 or 6239038 or 6241825 or 6251250 or 6244121 or 6277753 or 6286231 or 6305677 or 6334266 or 6344174 or 6388317 or 6389677 or 6418956 or 6436824 or 6454945 or 6464790).pn.

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

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Remarks

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Non US Patent and Publication references shall be filed under a separate paper transmittal. The current electronic filing contains part 3 out of a total of 4 electronic filings.

Signature

Examiner Name	Date		